

10/07b, 244

L Number	Hits	Search Text	DB	Time stamp
1	5	((polyacetylene (polyparaphenylen adj vinylene) ppv polyaniline) near4 dope\$2) and @ad<20000707 and (polymer near3 (plug ball bump))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/01 15:31
2	2	("4692225").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/01 15:32
3	1	(("4692225").PN.) and dope\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/01 15:32
-	12	(("5923955") or ("5891756") or ("5795818") or ("5904859") or ("5767009") or ("5804876")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/01 12:34
-	0	((nickel adj carbonyl) nico4) and @ad<20020213 and ((polymer epoxy dielectric) adj plug) and (semiconductor chip die dice ic (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 15:33
-	1009	((nickel adj carbonyl) nico4) and @ad<20020213	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 15:33
-	159	(((nickel adj carbonyl) nico4) and @ad<20020213) and (semiconductor chip die dice ic (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 15:34
-	0	(((nickel adj carbonyl) nico4) and @ad<20020213) and (semiconductor chip die dice ic (integrated adj circuit))) and ((copper cu) near3 (bump ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 15:34
-	159	(((nickel adj carbonyl) nico4) and @ad<20020213) and (semiconductor chip die dice ic (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 17:07
-	2560	((438/108) or (257/778)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 17:08
-	165	(((438/108) or (257/778)).CCLS.) and @ad<20020213 and ((ball bump) near3 (polymer epoxy)) and conductive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/25 12:01
-	165	(((438/108) or (257/778)).CCLS.) and @ad<20020213 and ((ball bump) near3 (polymer epoxy)) and conductive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/25 12:02

-	17	(polyacetylene (polyparaphenylene adj vinylene) ppv polyaniline) and @ad<20000707 and (polymer near3 (plug ball bump))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/01 15:26
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